MOSFETs Silicon P-Channel MOS (U-MOSVI)

# **TPC8129**

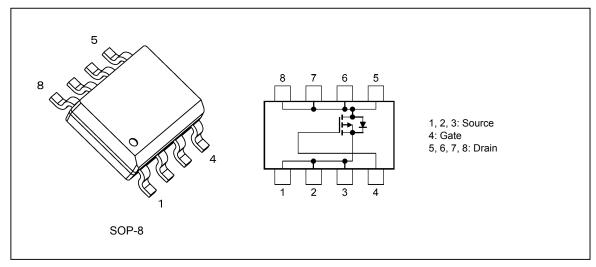
#### 1. Applications

- Lithium-Ion Secondary Batteries
- Power Management Switches

#### 2. Features

- (1) Small footprint due to a small and thin package
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 17 \text{ m}\Omega$  (typ.) ( $V_{GS} = -10 \text{ V}$ )
- (3) Low leakage current:  $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -30 \ V)$
- (4) Enhancement mode:  $V_{th}$  = -0.8 to -2.0 V ( $V_{DS}$  = -10 V,  $I_D$  = -0.2 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics				Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	-30	V
Gate-source voltage			V <sub>GSS</sub>	-25/+20	
Drain current (DC)		(Note 1)	I <sub>D</sub>	-9	А
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	-36	
Power dissipation	(t = 10 s)	(Note 2)	PD	1.9	W
Power dissipation	(t = 10 s)	(Note 3)	PD	1.0	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	21	mJ
Avalanche current			I <sub>AR</sub>	-9	А
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

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Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

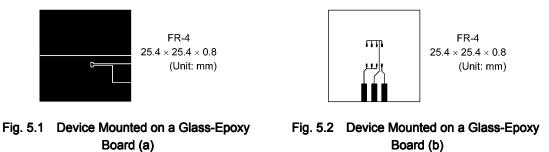
Characteristics			Symbol	Max	Unit
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	65.7	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	125	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{DD}$  = -24 V,  $T_{ch}$  = 25°C (initial), L = 0.2 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -9 A



Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

### 6. Electrical Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

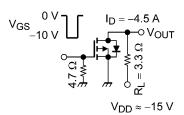
#### 6.1. Static Characteristics

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20 V, $V_{DS}$ = 0 V	_	_	±0.1	μA
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = -30 V, V <sub>GS</sub> = 0 V	_	_	-10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-30	_	_	V
Drain-source breakdown voltage (Note 5)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 10 V	-21	_	—	
Gate threshold voltage	V <sub>th</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -0.2 mA	-0.8	—	-2.0	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -4.5 A	_	22	28	mΩ
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -4.5 A	_	17	22	

Note 5: If a forward bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drainsource breakdown voltage is lowered in this mode.

#### 6.2. Dynamic Characteristics

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	1650	—	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	260	_	
Output capacitance	C <sub>oss</sub>		_	300	_	
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.	_	8	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	16	_	
Switching time (fall time)	t <sub>f</sub>		_	42	_	
Switching time (turn-off time)	t <sub>off</sub>		_	140	_	



Duty  $\leq$  1%,  $t_W^{}=$  10  $\mu s$ 

#### Fig. 6.2.1 Switching Time Test Circuit

#### 6.3. Gate Charge Characteristics

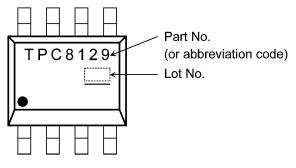
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -24$ V, $V_{GS}$ = -10 V, $I_D$ = -9 A	_	39	_	nC
Gate-source charge 1	Q <sub>gs1</sub>		_	4	_	
Gate-drain charge	Q <sub>gd</sub>		_	10	_	

#### 6.4. Source-Drain Characteristics

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulsed reverse drain current	(Note 6)	I <sub>DRP</sub>	_	_	_	-36	Α
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = -9 A, V <sub>GS</sub> = 0 V			1.2	V

Note 6: Ensure that the channel temperature does not exceed 150°C.

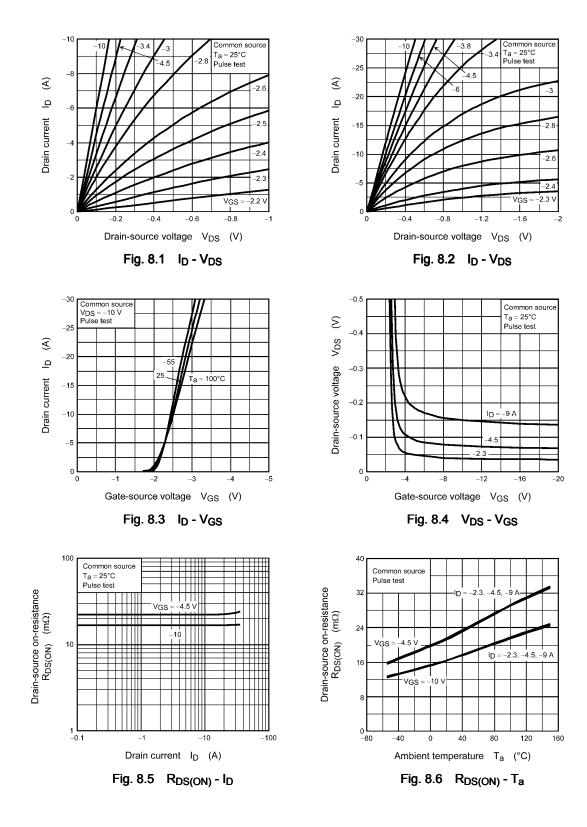
### 7. Marking (Note)

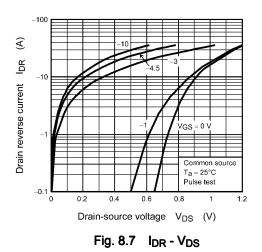


#### Fig. 7.1 Marking

- Note: A line under a Lot No. identifies the indication of product Labels. Not underlined: [[Pb]]/INCLUDES > MCV Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]] Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27, January 2003 on
  - The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

#### 8. Characteristics Curves (Note)





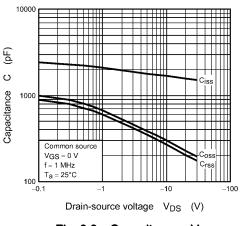


Fig. 8.8 Capacitance - VDS

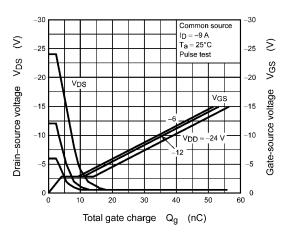


Fig. 8.10 Dynamic Input/Output Characteristics

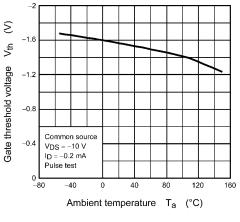
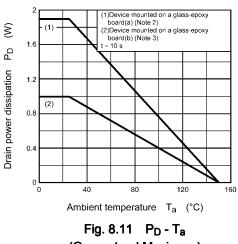
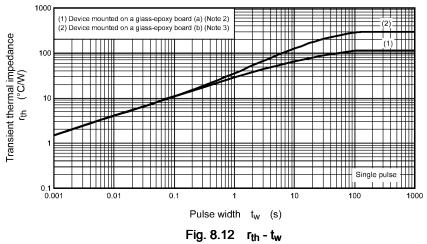


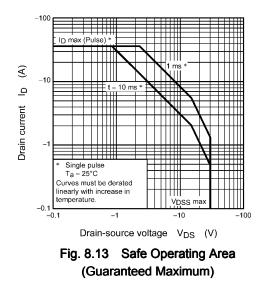
Fig. 8.9 V<sub>th</sub> - T<sub>a</sub>



(Guaranteed Maximum)



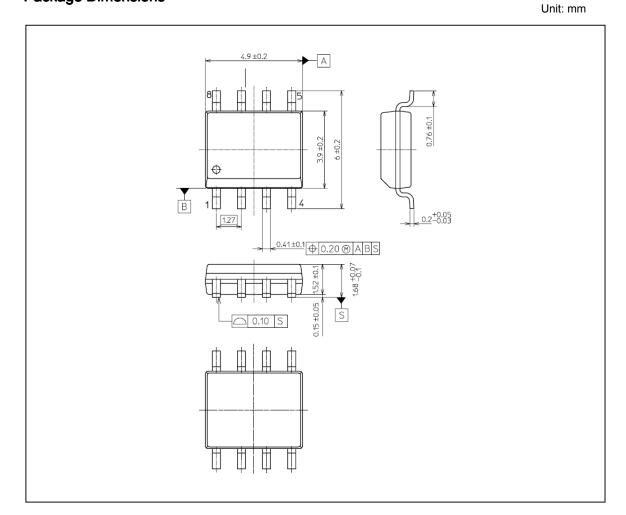
(Guaranteed Maximum)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

### **Package Dimensions**

**TPC8129** 



#### Weight: 0.085 g (typ.)

Package Name(s)
TOSHIBA: 2-5R1S
Nickname: SOP-8

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